IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of: **FUKASAWA, et al.**

Serial No.: **09/766,656**

Filed: **January 23, 2001**

Group Art Unit: **2814**

Prior Examiner: **D. Graybill**

P.T.O. Confirmation No.: 1144

FOR: **METHOD AND MOLD FOR MANUFACTURING SEMICONDUCTOR DEVICE, SEMICONDUCTOR DEVICE, AND METHOD FOR MOUNTING THE DEVICE**

AMENDMENT TRANSMITTAL

Commissioner for Patents
Washington, D.C. 20231

November 26, 2002

Sir:

Transmitted herewith is an Amendment in the above-identified application. The fee has been calculated as shown below:

	CLAIMS AS AMENDED						
	Claims Remaining After Amendment	Highest Number Previously Paid For		Present Extra	Small Entity	Large Entity	Additional Fee
Total Claims	23	20	=	3	X $9	X $18	54.00
Independent Claims	6	8	=	0	X $42	X $84	0
First Presentation of Multiple Dependent Claims					$140	280	
						TOTAL FEES ENCLOSED:	$54.00

XX Enclosed please find our check in the amount of $54.00 for the additional claims fee in connection with this amendment.

XX The Commissioner is hereby authorized to charge payment for any additional fees associated with this communication or credit any overpayment to Deposit Account No. 01-2340. Two duplicates of this sheet are attached.

Respectfully submitted,

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SGA/arf
Atty. Docket No. **980233B**
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#8C Pre-Amdt. M. Bauer 4/29/03

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SECOND SUPPLEMENTAL PRELIMINARY AMENDMENT

Commissioner for Patents
Washington, D.C. 20231

Date: November 26, 2002

Sir:

Further to the Supplemental Preliminary Amendment filed February 21, 2002, please amend the above-captioned patent application as follows:

IN THE CLAIMS:

Please add new claims 111-120 as follows:

111. A method for fabricating a semiconductor device comprising:

a resin sealing step of loading a wiring board having a flexible member on which a semiconductor element and leads are arranged onto a mold and supplying sealing resin to the semiconductor element so as to seal the semiconductor element; and

a protruding electrode forming step of forming protruding electrodes so as to be